

3.0x2.0mm SURFACE MOUNT LED LAMP

Part Number: AA3020SURCK

Hyper Red

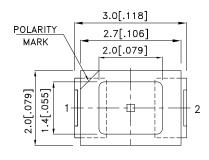
Features

- 3.0mm x 2.0mm, 1.4mm high, only minimum space required.
- Suitable for compact optoelectronic applications.
- Low power consumption.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 4.
- RoHS compliant.

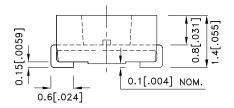
Description

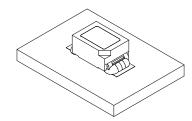
The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

Package Dimensions









- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- Specifications are subject to change without notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.





SPEC NO: DSAD1214 APPROVED: WYNEC

REV NO: V.5 CHECKED: Allen Liu DATE: OCT/05/2009 DRAWN: F.F.Zhou

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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] ens Type @ 20mA		Viewing Angle [1]
		2.	Min.	Тур.	201/2
AA3020SURCK	Hyper Red (AlGaInP)	WATER CLEAR	70	200	90°

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	650		nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Red	630		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	28		nm	IF=20mA
С	Capacitance	Hyper Red	35		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red	1.95	2.5	V	IF=20mA
lR	Reverse Current	Hyper Red		10	uA	V _R =5V

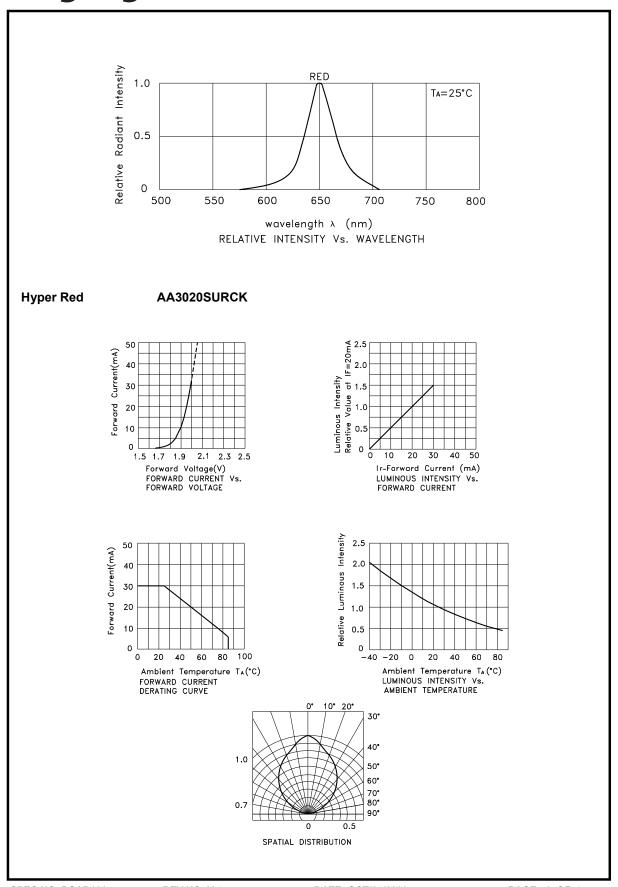
- Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

gg						
Parameter	Hyper Red					
Power dissipation	75	mW				
DC Forward Current	30	mA				
Peak Forward Current [1]	185	mA				
Reverse Voltage	5	V				
Operating Temperature	-40°C To +85°C					
Storage Temperature	-40°C To +85°C					

Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

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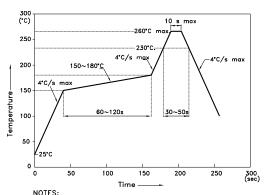
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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



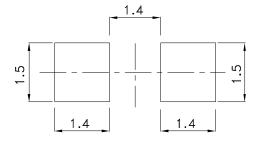
NOTES:

1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

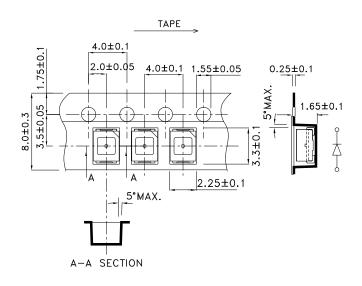
2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

3.Number of reflow process shall be 2 times or less.

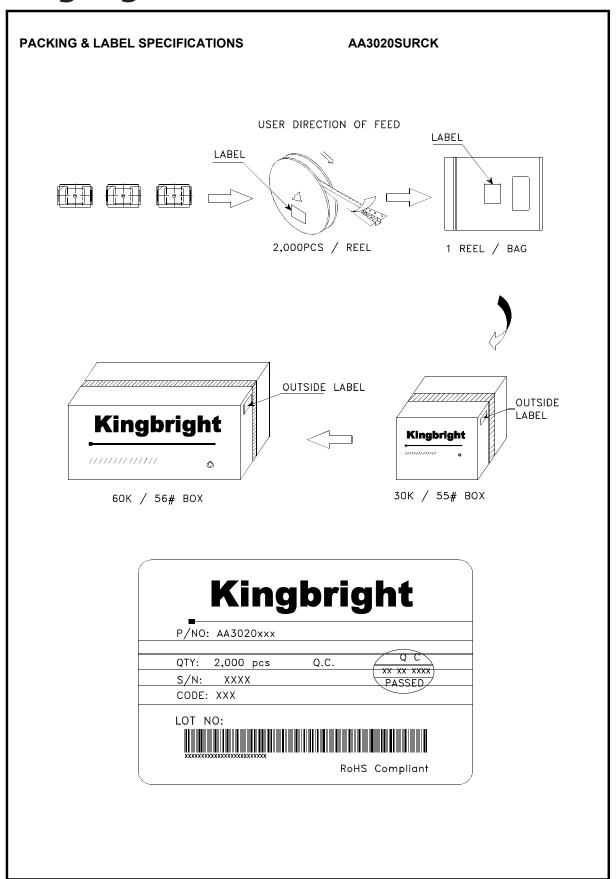
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units: mm)



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